GENERAL DESCRIPTION

Passivated, sensitive gate triac in a full pack plastic envelope, intended for use in general purpose bidirectional switching and phase control applications. This device is intended to be interfaced directly to microcontrollers, logic integrated circuits and other low power gate trigger circuits.

PINNING - SOT186A

PIN	DESCRIPTION
1	main terminal 1
2	main terminal 2
3	gate
case	isolated

QUICK REFERENCE DATA

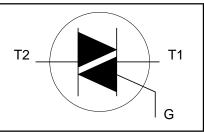
SYMBOL	PARAMETER	MAX.	UNIT
V _{drm}	Repetitive peak off-state voltages	600	V
I _{t(rms)}	RMS on-state current	8	A
I _{tsm}	Non-repetitive peak on-state current	65	A

PIN CONFIGURATION

case

O





LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{DRM}	Repetitive peak off-state voltages		-	600 ¹	V
I _{T(RMS)} I _{TSM}	RMS on-state current Non-repetitive peak on-state current	full sine wave; $T_{hs} \le 73 \degree C$ full sine wave; $T_j = 25 \degree C$ prior to surge	-	8	A
		t = 20 ms	-	65	A
l²t dl _⊤ /dt	I ² t for fusing Repetitive rate of rise of on-state current after	t = 16.7 ms t = 10 ms $I_{TM} = 12 \text{ A}; I_G = 0.2 \text{ A};$ $dI_G/dt = 0.2 \text{ A}/\mu \text{s}$	-	71 21	A A²s
	triggering	T2+ G+ T2+ G- T2- G- T2- G+		50 50 50 10	A/μs A/μs A/μs A/μs
I _{GM} V _{GM} P _{GM}	Peak gate current Peak gate voltage Peak gate power	12-04	-	2 5 5	À V W
P _{G(AV)} T _{stg} T _j	Average gate power Storage temperature Operating junction temperature	over any 20 ms period	- -40 -	0.5 150 125	ວໍລໍ&

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¹ Although not recommended, off-state voltages up to 800V may be applied without damage, but the triac may switch to the on-state. The rate of rise of current should not exceed 6 $A/\mu s$.

Triacs	
logic level	

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ISOLATION LIMITING VALUE & CHARACTERISTIC

 $T_{hs} = 25$ °C unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _{isol}	R.M.S. isolation voltage from all three terminals to external heatsink	f = 50-60 Hz; sinusoidal waveform; R.H. ≤ 65% ; clean and dustfree	-	-	2500	V
C _{isol}	Capacitance from T2 to external heatsink	f = 1 MHz	-	10	-	pF

THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
R _{th j-hs} R _{th j-a}	Thermal resistance junction to heatsink Thermal resistance junction to ambient	full or half cycle with heatsink compound without heatsink compound in free air	- - -	- - 55	4.5 6.5 -	K/W K/W K/W

STATIC CHARACTERISTICS

 $T_i = 25$ °C unless otherwise stated

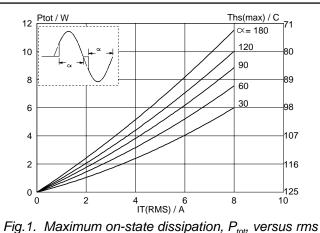
SYMBOL	PARAMETER	CONDITIONS		MIN.	TYP.	MAX.	UNIT
I _{GT}	Gate trigger current	$V_{\rm D} = 12 \text{ V}; I_{\rm T} = 0.1 \text{ A}$					
01			T2+ G+	-	2.5	5	mA
			T2+ G-	-	3.5	5	mA
			T2- G-	-	3.5	5	mA
			T2- G+	-	6.5	10	mA
I _L	Latching current	$V_{\rm D} = 12 \text{ V}; I_{\rm GT} = 0.1 \text{ A}$					
-			T2+ G+	-	1.6	15	mA
			T2+ G-	-	8.5	20	mA
			T2- G-	-	1.2	15	mA
			T2- G+	-	2.5	20	mA
I _H	Holding current	$V_{\rm D} = 12 \text{ V}; I_{\rm GT} = 0.1 \text{ A}$		-	1.5	10	mA
I _H V⊤	On-state voltage	$I_{T} = 10 \text{ A}$		-	1.3	1.65	V
V _{GT}	Gate trigger voltage	$V_{\rm D} = 12 \text{ V}; I_{\rm T} = 0.1 \text{ A}$		-	0.7	1.5	V
-		$V_{\rm D} = 400 \text{ V}; I_{\rm T} = 0.1 \text{ A}; T_{\rm i} = 125$	°C	0.25	0.4	-	V
I _D	Off-state leakage current	$V_{D}^{i} = 400 \text{ V}; I_{T} = 0.1 \text{ A}; T_{j} = 125$ $V_{D}^{i} = V_{DRM(max)}; T_{j} = 125 ^{\circ}\text{C}$		-	0.1	0.5	mA

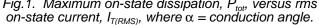
DYNAMIC CHARACTERISTICS

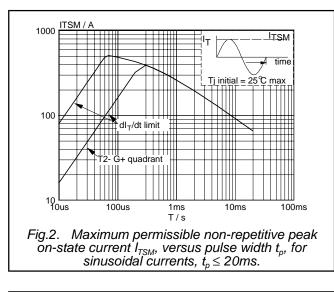
 $T_j = 25$ °C unless otherwise stated

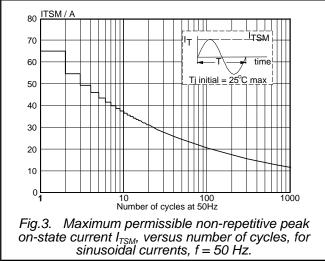
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
	off-state voltage	$V_{DM} = 67\% V_{DRM(max)}; T_j = 125 °C;$ exponential waveform; $R_{GK} = 1 k\Omega$	-	5	-	V/µs
t _{gt}	Gate controlled turn-on time	$I_{TM} = 12 \text{ A}; V_D = V_{DRM(max)}; I_G = 0.1 \text{ A}; dI_G/dt = 5 \text{ A}/\mu \text{s}$	-	2	-	μs

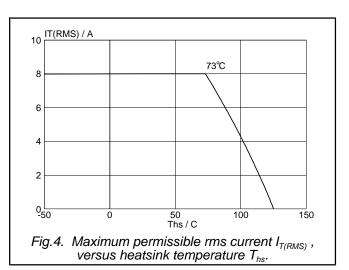
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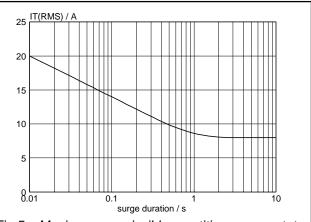
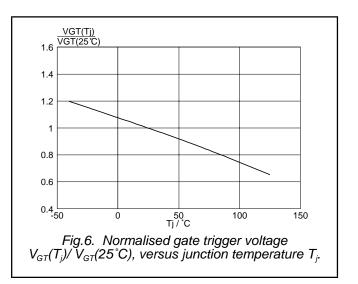
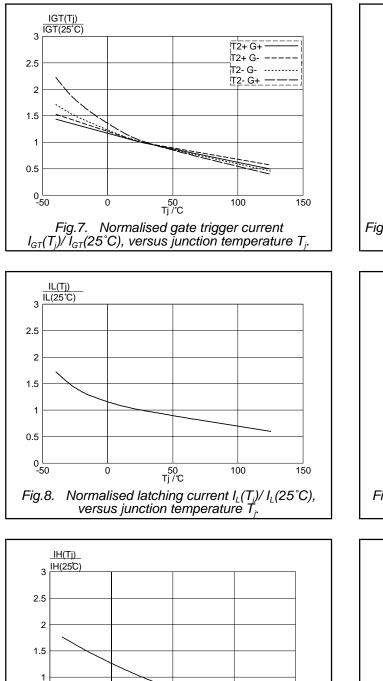


Fig.5. Maximum permissible repetitive rms on-state current $I_{T(RMS)}$, versus surge duration, for sinusoidal currents, f = 50 Hz; $T_{hs} \le 73$ °C.



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50 Tj /℃

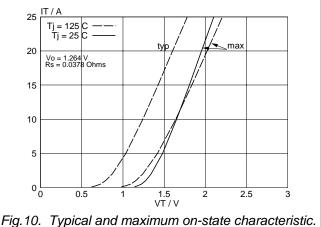
Fig.9. Normalised holding current $I_{H}(T_{i})/I_{H}(25^{\circ}C)$,

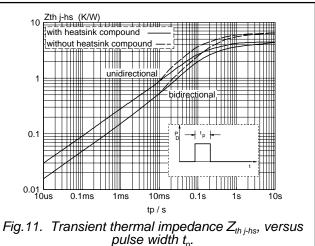
versus junction temperature 1

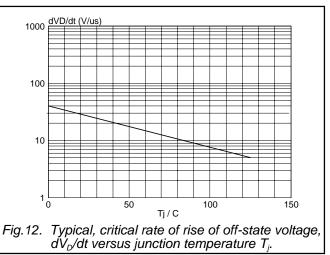
0

100

150





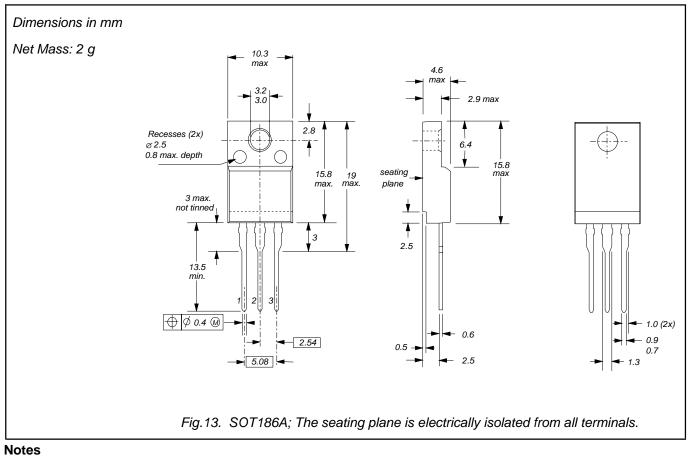


0.5

0∟ -50

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MECHANICAL DATA



Refer to mounting instructions for F-pack envelopes.
Epoxy meets UL94 V0 at 1/8".

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DEFINITIONS

DATA SHEET STA	TUS	
DATA SHEET STATUS2PRODUCT STATUS3		DEFINITIONS
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice
Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in ordere to improve the design and supply the best possible product
Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Changes will be communicated according to the Customer Product/Process Change Notification (CPCN) procedure SNW-SQ-650A

Limiting values

Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

Where application information is given, it is advisory and does not form part of the specification.

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² Please consult the most recently issued datasheet before initiating or completing a design.

³ The product status of the device(s) described in this datasheet may have changed since this datasheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.